New thermal mechanisms in sub-10nm structures

Sebastian Volz

Laboratoire d'Energétique Moléculaire et Macroscopique, Combustion

CNRS - Ecole Centrale Paris - France







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PHONON PARTICLE/PHONON WAVE

$\Delta k.\Delta x > 2\pi$





$\Delta k < p/a => \Delta x > 10a = 5nm$

New thermal mechanisms in sub-10nm structures

1. Heat Conduction in Nanowires





2. 3D atomic scale phononic crystals

3. Transient Non Fourier Heat Conduction



1-Nanowires and Thermal Contact Resistances



Metrology





Spectrometry



NanoElectronics



Molecular Junction







IF CONTACT CROSS SECTION < PHONON WAVELENGTH?

M.R. says:

not obtained for long wires

Wire Thermal Conductance

Quantum of Conductance

-Conductance of 1 phonon BRANCH /NOT/ 1 Quantum

-Temperature Dependent

-Predominant <u>CONDUCTANCE</u>?

CONTACT CONDUCTANCE

$$Q = G \cdot (T_w - T_b)$$
$$G = \frac{1}{2} \{ t_b C_b v_b + t_w C_w v_w \}$$

$$t_w = \frac{C_b v_b}{C_b v_b + C_w v_w}$$

Diffuse Transmission: Phonons loose memory at interface => MAXIMUM FLUX $\frac{1}{G} = \frac{1}{C_w v_w} + \frac{1}{C_b v_b}$

$$C_{b}v_{b} = \frac{\partial Q_{b}}{\partial T} = \pi g_{3D} \sum_{m} \int_{\|\mathbf{k}\|} \hbar \omega_{m,\mathbf{k}} \frac{\partial \tilde{n}}{\partial T} v_{m,\mathbf{k}} k^{2} d\|\mathbf{k}\|$$
$$C_{w}v_{w} = \frac{\partial Q_{w}}{\partial T} = g_{1D} \sum_{m} \int_{\|\mathbf{k}\|} \hbar \omega_{m,\mathbf{k}} \frac{\partial \tilde{n}}{\partial T} v_{m,\mathbf{k}} d\|\mathbf{k}\|$$

DISPERSION CURVES

Lattice dynamics

Motion Equation **Solution**:

$$m_k \ddot{u}_{lk_{\mu}} = \sum_{l'k',\nu} \phi_{lk_{\mu},l'k'_{\nu}} u_{l'k'_{\nu}}$$

$$\omega^{2}(\mathbf{q})e_{k\mu} = \sum_{k',\nu} D_{\mu\nu} \begin{pmatrix} \mathbf{q} \\ kk' \end{pmatrix} e_{k\mu}$$
Ve

Plane Monochromatic Way

WIRE vs CONTACT

CONTACT RESISTANCE PREDOMINANT 2 ODM

CONCLUSION Nanowire and Contact

Heat flux in of SUB-10nm NANOWIRES is dominated by CONTACT RESISTANCE

QUANTUM THERMAL CONDUCTANCE CAN NOT BE MEASURED IN THOSE WIRES

2 to 5 Orders of Magnitude Difference between Resistances

Thermal resistance of wave effects much larger than <u>Fourier</u> and *Wexler* Resistances

Might be interesting for thermoelectrics or insulating materials

The shape of the contact has significant impact

3D-PHONONIC CRYSTALS

3D PHONONIC CRYSTALS TO GENERATE GAPS IN PHONON SPECTRA?

THERMAL PHONONS λ~1nm => ATOMIC SCALE PERIOD

STRUCTURE

Ge in Si

5 Lattice Constants Cubic NanoParticles

SW potential

Periodic Boundaries Lattice Dymamics

THERMAL CONDUCTIVITY

$$\lambda = \frac{1}{3} \frac{\hbar}{2\pi^2} \sum_{m} \int_{0}^{2\pi/d} \Lambda_{k,m} k^2 \omega_{k,m} \frac{\partial n_{k,m}^{(0)}}{\partial T} |v_{k,m}| dk$$

$$\lambda \approx \frac{1}{3} \langle \Lambda \rangle \langle C_p v \rangle$$

$$\begin{split} \left\langle C_p v \right\rangle &= \frac{\hbar}{2\pi^2} \sum_{m=1}^{N_m} \int_0^{2\pi/d} k^2 \omega_{k,m} \frac{\partial n_{k,m}^{(0)}}{\partial T} \left| v_{k,m} \right| dk \\ \left\langle \Lambda \right\rangle &= \frac{d}{2\pi N_m} \sum_{m=1}^{N_m} \int_0^{2\pi/d} \Lambda_{k,m} dk, \end{split}$$

DISPERSION CURVES

<Cp.v>

CONCLUSION 3D Phononic Crystals

NO PHONON GAP but 1 ORDER OF MAGNITUDE Decrease Of GROUP VELOCITY

PRESUMPTION OF MFP DECREASE By 1-2 ORDER OF MAGNITUDE

POSSIBLE CONDUCTIVITY DECREASE by FACTOR 1000 = 0.1 W/mK! LESS THAN ALLOY, GLASS and WATER

3- TRANSIENT NON FOURIER CONDUCTION

$$\frac{T(x,t) - T_0}{T_{Bound} - T_0} = erfc\left(\frac{x}{\sqrt{4\alpha t}}\right)$$

Cattaneo-Vernotte Model: Inertia

$$\tau$$
.dq/dt + q = $-\lambda$. gradT

T(x=0,t)

NEVER PROVED EXPERIMENTALLY

EXPERIMENT

Shell

CORE Pump-Probe Femtolaser Relaxing on Core Phonons **Conduction to Shell** Shell Heat conduction: Fourier or Non-Fourier 100 nm

Gold

⊘9nm

Nanoparticle

Silica

old

2-STEP+BALLISTIC-DIFFUSIVE MODELS

$$C_{e}\frac{\partial T_{e}}{\partial t} = -G\left(T_{e} - T_{l}\right) + P_{vol}(t)$$

Shell
CORE
$$H(t) = \int_{S_p} \mathbf{q}(\mathbf{r}, t) \cdot \mathbf{n} \, ds$$

$$V_p C_l \frac{\partial T_l}{\partial t} = V_p G (T_e - T_l) - H(t)$$

R

STIC-DIFFUSIVE EQUATION

$$C\left(\tau \frac{\partial^2 T_m}{\partial t^2} + \frac{\partial T_m}{\partial t}\right) = \nabla(k\nabla T_m) - \nabla \cdot \mathbf{q}_b$$

$$+ \left(\dot{q}_e + \tau \frac{\partial \dot{q}_e}{\partial t}\right),$$

$$\mathbf{q}_b(t,\mathbf{r}) = \frac{1}{4\pi} \int \left[\int |\mathbf{v}| \hbar \omega D(\omega) f_w [t - (s - s_0)/|\mathbf{v}|, \mathbf{r} - (s - s_0)\hat{\Omega}] \exp\left(-\int_{s_0}^s \frac{ds}{|\mathbf{v}|\tau}\right) \cos\theta \, d\Omega \right] d\omega$$

BDE/FOURIER

Shell Thickness

STRONG DEPENDENCE TO SHELL THICKNESS

CONCLUSION on TRANSIENT NON FOURIER

EXPERIMENTAL ACCESS TO TRANSIENT NON-FOURIER HEAT CONDUCTION

By USING CORE-SHELL STRUCTURES

WAS NEVER SHOWN AT AMBIENT TEMPERATURE

NEED A SHELL WITH LONG MFP

Collaborators

Post-Doc Students

M. Rachidi

J.-N. Gillet

E. Rousseau

Ph.D. Students

Y. Chalopin

P.-O. Chapuis

C. Bera

Academic:

J.-J. Greffet, EM2C-ECP M. Laroche, EM2C-ECP M. Massot, EM2C-ECP J. Bai, LMSSMAT-ECP

B. Palpant, INSP-Paris
J.-Y. Duquesne, INSP-Paris
L. Jullien, ENS Ulm Paris
Charlie Goss, LPN - Paris
M. Mortier, ENSCP-Paris
G. Tessier, ESPCI-Paris

S. Ravaine, ICMCB-Bordeaux S. Dilhaire, CPMOH Bordeaux

S. Gomès, CETHIL-Lyon S. Lefèvre, CETHIL-Lyon

G. Domingues, LT-Nantes B. Charlot, TIMA-Grenoble

C. Bergaud, LAAS-Toulouse

Industries/Institutes:

D. Rochais, CEA_Le Ripault

- N. Mingo, CEA-LITEN
- M. Plissonnier, CEA-LITEN

107 Topics in Applied Physics

THANK YOU !

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